

SEMICONDUCTOR PACKAGE WITH STACKED DIES

ABSTRACT OF THE DISCLOSURE

[0026] A semiconductor package comprising a plurality of leads. Each of the leads defines opposed first and second surfaces, and a third surface which is also disposed in opposed relation to the second surface. The first surface is oriented between the second and third surfaces. The semiconductor package further comprises first and second semiconductor dies which each define opposed first and second surfaces. Disposed on the first surface of the first semiconductor die are a plurality of bond pads, with bond pads also being disposed on the second surface of the semiconductor die. The first surface of the first semiconductor die is attached to the second surface of each of the leads, with the first surface of the second semiconductor die being attached to the second surface of the first semiconductor die. A plurality of conductive connectors or wires electrically connect the bond pads of the first and second semiconductor dies to respective ones of the leads. An encapsulating portion is applied to and at least partially encapsulates the leads, the first and second semiconductor dies, and the conductive connectors.